

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	586280	(carrier substrate board (printed circuit wiring) adj5 board) with (via hole opening)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/18 06:37
L2	99361	1 with (((bond bonding) with (pad electrode terminal)) pad terminal electrode)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/18 06:39
L3	102818	1 with (((bond bonding) with (pad electrode terminal)) land pad terminal electrode)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/18 06:39
L4	6891	1 with ((bond bonding) with (pad electrode terminal)) with (land pad terminal electrode)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/18 06:40
L5	2320	4 with wire	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/18 06:40
L6	1849	(die chip ic (integrated adj circuit) semiconductor) same 5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/18 06:41